

An IATF 16949, ISO9001 and ISO 14001/ISO 45001 Certified Company





SILICON BRIDGE RECTIFIERS

Reverse Voltage - 50 to 1000 Volts Forward Current - 15 Amperes







KBPC Leaded Metal Case Package

RoHS compliant

KBPC15005 ~ KBPC1510

FEATURES:

- 1. The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- 2. Low reverse leakage
- 3. High forward surge current capability
- 4. High temperature soldering guaranteed: 260 °C/10 seconds, at 5 lbs. (2.3kg) tension

ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C Unless otherwise specified)

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz,resistive or inductive load,for current capacitive load current derate by 20%

PARAMETERS	SYMBOL	KBPC 15005	KBPC 1501	KBPC 1502	KBPC 1504	KBPC 1506	KBPC 1508	KBPC 1510	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	٧
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward output rectified current at T_c = 55 °C	I _(AV)	15				Α			
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	300			А				
Maximum instantaneous forward voltage drop per bridge element at 7.5 Amp	V _F	1.1			Volts				
Maximum Reverse Current at Rate DC Blocking Voltage Per Element @T _J =25°C	I _R	10			μА				
Operating junction temperature range	T_J	-55 to +150			°C				
Storage temperature range	T _{STG}	-55 to +150			°C				







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TYPICAL CHARACTERISTICS CURVES

Fig. 1. Forward Current Derating Curve

Fig. 2. Typical Forward Characteristics

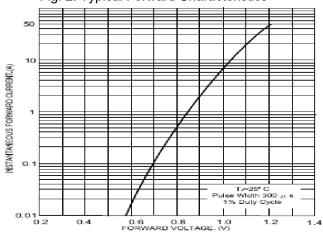


Fig. 4. Typical Junction Capacitance

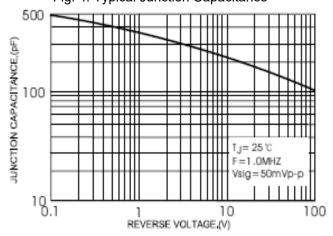


Fig. 5. Typical Reverse Characteristics

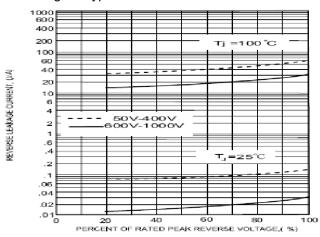
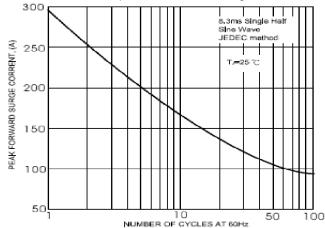


Fig. 3. Maximum Non-Repetitive Forward Surge Current



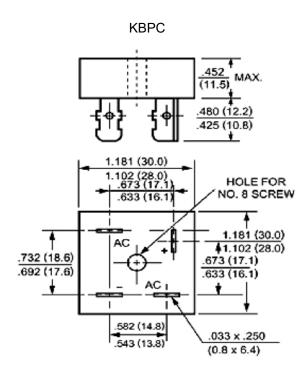








Package Details



Dimensions in inches and (millimeters)

MECHANICAL DATA

Case: Metal or molded plastic with heatsink integrally mounted in the bridge encapsulation

Terminals: Either plated 0.25" (6.35mm) Fasten lugs or plated copper leads 0.040" (1.02mm) diameter.

Mounting position: Thru hole for #8 screw mounting

Weight: 30 gram approx.







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Recommended Reflow Solder Profiles

The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.

Figure 1

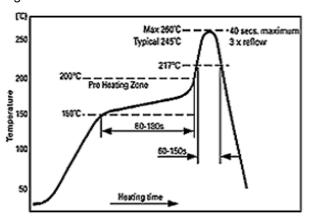
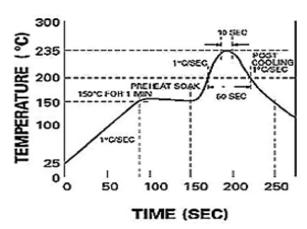


Figure 2



Reflow profiles in tabular form

Profile Feature	Sn-Pb System	Pb-Free System ~3°C/second		
Average Ramp-Up Rate	~3°C/second			
Preheat - Temperature Range - Time	150-170°C 60-180 seconds	150-200°C 60-180 seconds		
Time maintained above: – Temperature – Tim	200°C 30-50 seconds	217°C 60-150 seconds		
Peak Temperature	235°C	260°C max.		
Time within +0 -5°C of actual Peak	10 seconds	40 seconds		
Ramp-Down Rate	3°C/second max.	6°C/second max		





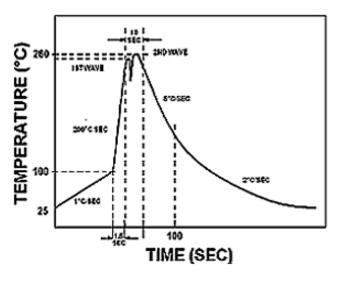


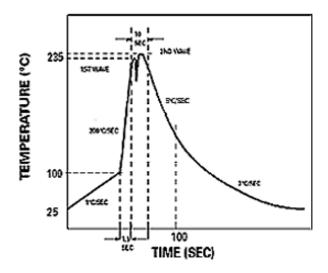
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Recommended Wave Solder Profiles

The Recommended solder Profile For Devices with Pb-free terminal plating where a Pb-free solder is used

The Recommended solder Profile For Devices with Pbfree terminal plating used with leaded solder, or for devices with leaded terminal plating used with leaded solder

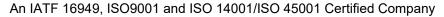




Wave Profiles in Tabular Form

Profile Feature	Sn-Pb System	Pb-free System		
Average Ramp-Up Rate	~200°C/second	~200°C/second		
Heating rate during preheat	Typical 1-2, Max 4°C/sec	Typical 1-2, Max 4°C/Sec		
Final preheat Temperature	Within 125°C of Solder Temp	Within 125°C of Solder Temp		
Peak Temperature	235°C	260°C max.		
Time within +0 -5°C of actual Peak	10 seconds	10 seconds		
Ramp-Down Rate	5°C/second max.	5°C/second max.		









Recommended Product Storage Environment for Discrete Semiconductor Devices

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- · Temperature 5 °C to 30 °C
- · Humidity between 40 to 70 %RH
- · Air should be clean.
- · Avoid harmful gas or dust.
- · Avoid outdoor exposure or storage in areas subject to rain or water spraying .
- · Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- · Avoid rapid change of temperature.
- · Avoid condensation.
- · Mechanical stress such as vibration and impact shall be avoided.
- · The product shall not be placed directly on the floor.
- The product shall be stored on a plane area. They should not be turned upside down. They should not be placed against the wall.

Shelf Life of CDIL Products

The shelf life of products is the period from product manufacture to shipment to customers. The product can be unconditionally shipped within this period. The period is defined as 2 years.

If products are stored longer than the shelf life of 2 years the products shall be subjected to quality check as per CDIL quality procedure.

The products are further warranted for another one year after the date of shipment subject to the above conditions in CDIL original packing.

Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start.

For this, the following JEDEC table may be referred:

JEDEC MSL Level				
Level	Time	Condition		
1	Unlimited	≤30 °C / 85% RH		
2	1 Year	≤30 °C / 60% RH		
2a	4 Weeks	≤30 °C / 60% RH		
3	168 Hours	≤30 °C / 60% RH		
4	72 Hours	≤30 °C / 60% RH		
5	48 Hours	≤30 °C / 60% RH		
5a	24 Hours	≤30 °C / 60% RH		
6	Time on Label(TOL)	≤30 °C / 60% RH		







Customer Notes

Component Disposal Instructions

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL wil not be responsible for any damages resulting from such sale(s).

CDIL strives for continuous improvement and reserves the right to change the specifications of its products without prior notice.



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